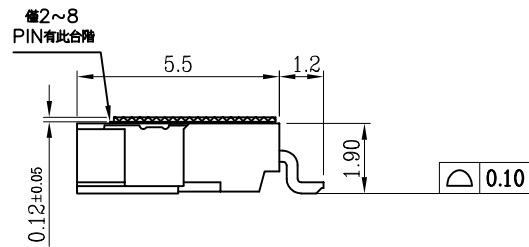
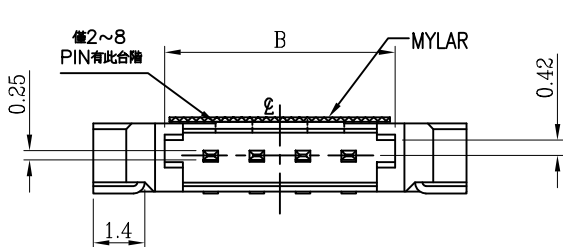


RECOMMENDED P.C. BOARD PATTERN DIM. (REF.)



- NOTES:
 1. MATERIAL:
 1.1 HOUSING: HALOGEN FREE PLASTIC,UL94V-0.
 1.2 CONTACT: COPPER ALLOY
 1.3 FITTING NAIL: COPPER ALLOY

2. FINISH:
 2.1 CONTACT:
 1: 50u"~100u" NICKEL UNDER PLATING OVER ALL GOLD FLASH ON CONTACT AREA
 L: 50u"~100u" NICKEL UNDER PLATING OVER ALL 80u"~120u" PURE TIN ON CONTACT AREA
 N: 50u"~100u" NICKEL UNDER PLATING OVER ALL 80u"~120u" MATT TIN ON CONTACT AREA
 C: 50u"~100u" NICKEL UNDER PLATING OVER ALL 15u" MIN GOLD ON CONTACT AREA
 W: 100u"~150u" NICKEL UNDER PLATING OVER ALL 15u" MIN GOLD ON CONTACT AREA
 D: 100u"~150u" NICKEL UNDER PLATING OVER ALL 30u" MIN GOLD ON CONTACT AREA
 T: 100u"~150u" NICKEL UNDER PLATING OVER ALL 10u" MIN GOLD ON CONTACT AREA

- 2.2 SOLDER:
 1: 50u"~100u" NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
 L: 50u"~100u" NICKEL UNDER PLATING OVER ALL 80u"~120u" PURE TIN ON SOLDER AREA
 N: 50u"~100u" NICKEL UNDER PLATING OVER ALL 80u"~120u" MATT TIN ON SOLDER AREA
 C: 50u"~100u" NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
 W: 100u"~150u" NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
 D: 100u"~150u" NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
 T: 100u"~150u" NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA

- 2.3 FITTING NAIL:
 1: 50u"~100u" NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER TAILS
 L: 50u"~100u" NICKEL UNDER PLATING OVER ALL 100u"~150u" PURE TIN ON SOLDER TAILS
 N: 50u"~100u" NICKEL UNDER PLATING OVER ALL 100u"~150u" MATT TIN ON SOLDER TAILS
3. REFLOW SOLDER CAPABLE TO 260°C
 PER ACES SPEC.
 4. SPEC. PLS. REFER TO PS-50278-XXXX-XXX
 5. PACKAGE PLS. REFER TO 88230-XX0X-TRP
 6. PART NUMBER

P/N LEGEND

50278-XXX	X	X-XXX	XXX	COLOR	PACKING
			001	BLACK	88230-XX0X-TRP
			002	NATURE	88230-XX0X-TRP
			003	BLACK	88230-XX0X-TRP

- NO OF CKT
- PACKING
 O:TAPE&REEL(2~10PIN WITH MYLAR)
 (OTHER WITHOUT MYLAR)
 1:TUBE(2~10PIN WITH MYLAR)
 (OTHER WITHOUT MYLAR)
 T:TAPE & REEL(WITHOUT MYLAR)
 U:TUBE(WITHOUT MYLAR)
- PLATING
 L: PURE TIN
 1: GOLD FLASH
 N: MATT TIN
 C: CONTACT AREA:15u" GOLD PLATING
 SOLDER AREA: GOLD FLASH
 W: CONTACT AREA:15u" GOLD PLATING
 SOLDER AREA: GOLD FLASH
 D:30u" GOLD ON CONTACT(LEAD FREE)
 SOLDER AREA: GOLD FLASH
 T:10u" GOLD ON CONTACT(LEAD FREE)
 SOLDER AREA: GOLD FLASH

CKT.	DIM A	DIM B	DIM C	M/s(W)±0.15
2	1.25	3.77	7.65	3.00
3	2.50	5.02	8.90	3.00
4	3.75	6.27	10.15	6.00
5	5.00	7.52	11.40	6.00
6	6.25	8.77	12.65	6.00
7	7.50	10.02	13.90	10.00
8	8.75	11.27	15.15	10.00
9	10.00	12.52	16.40	10.00
10	11.25	13.77	17.65	12.00
11	12.50	15.02	18.90	X
12	13.75	16.27	20.15	X
14	16.25	18.77	22.65	X
15	17.50	20.02	23.90	X
16	18.75	21.27	25.15	X

QUALITY SYMBOLS
 MAJOR Ⓢ
 CRITICAL Ⓢ

GENERAL TOLERANCES
 (UNLESS SPECIFIED)
 X. ±0.5
 .X ±0.25
 .XX ±0.15
 .XXX ±0.1
 ANGLES ±2°

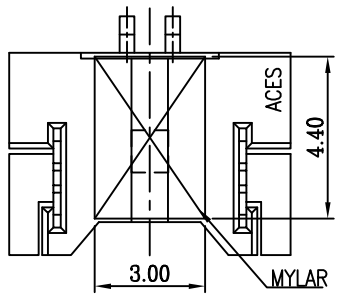
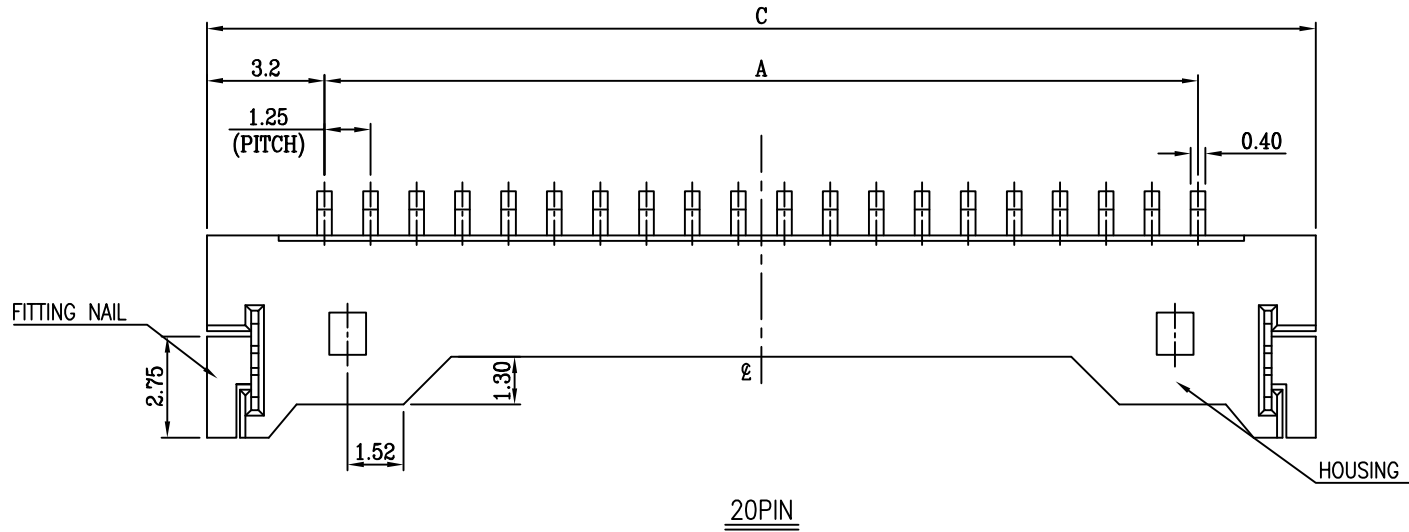
DRAWN BY: JINTAO DATE: 20/04/22
 CHECKED BY: DATE: 20/04/22
 BRAVE DATE: 20/04/22
 APPROVED BY: BRAVE DATE: 20/04/22

UNITS: mm
 SCALE: 1:1
 SHEET NO.: 1 OF 2

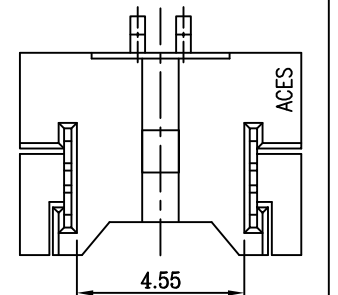
ACES ELECTRONICS

TITLE: 1.25mm WIRE TO BOARD CONN. LFP-2 SMT R/A TYPE

RFQ NO.: N/A
 DWG NO.: 50278-XXXX-XXX



2PIN WITH MYLAR



2PIN WITHOUT MYLAR

CKT.	DIM A	DIM B	DIM C	M/s(W)
20	23.75	26.27	30.15	X

QUALITY SYMBOLS MAJOR CRITICAL	DRAWN BY JINTAO	DATE 20/04/22	
	CHECKED BY BRAVE	DATE 20/04/22	
GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	APPROVED BY BRAVE	DATE 20/04/22	TITLE 1.25mm WIRE TO BOARD CONN. LPF-2 SMT R/A TYPE
	UNITS mm		SIZE A4
SCALE 1 : 1	SHEET NO. 2 OF 2	REV P	DWG NO. 50278-XXXXX-XXX